



Final Product Change Notification

201909023F01

Issue Date: 27-Oct-2019
Effective Date: 24-Jan-2020

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QUALITY

Management Summary

LPC540xx will be sourced from die revision 1B.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

LPC540xx Revision
Change from 0A to 1B

Description of Change

Microcontroller products LPC540xx will be sourced from the new product revision 1B to resolve multiple errata items.

Product revision 1B resolves the following errata as described in the device errata sheet, https://www.nxp.com/docs/en/errata/ES_LPC540xx.pdf
ISP.1, OTP.1, OTP.2, USB.1, USB.3, IOCON.1, ROM.1 and USB.ROM.1.

Reason for Change

To fix the functional deviations ISP.1, OTP.1, OTP.2, USB.1, USB.3, IOCON.1, ROM.1 and USB.ROM.1 as documented in the errata sheet.

Identification of Affected Products

Top side marking
The last 2 characters of the last line in the top side marking changes from "0A" to "1B"

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 28-Dec-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No change to form, fit or function other than the fixed errata items

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 25-Nov-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors

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Affected OPN

Affected 12NC

LPC54005JBD100E	935350936551
LPC54005JET100E	935350937551
LPC54016JBD100E	935350938551
LPC54018JET180E	935350943551
LPC54016JET180E	935350941551
LPC54018JBD208E	935350942551
LPC54016JBD208E	935350939551